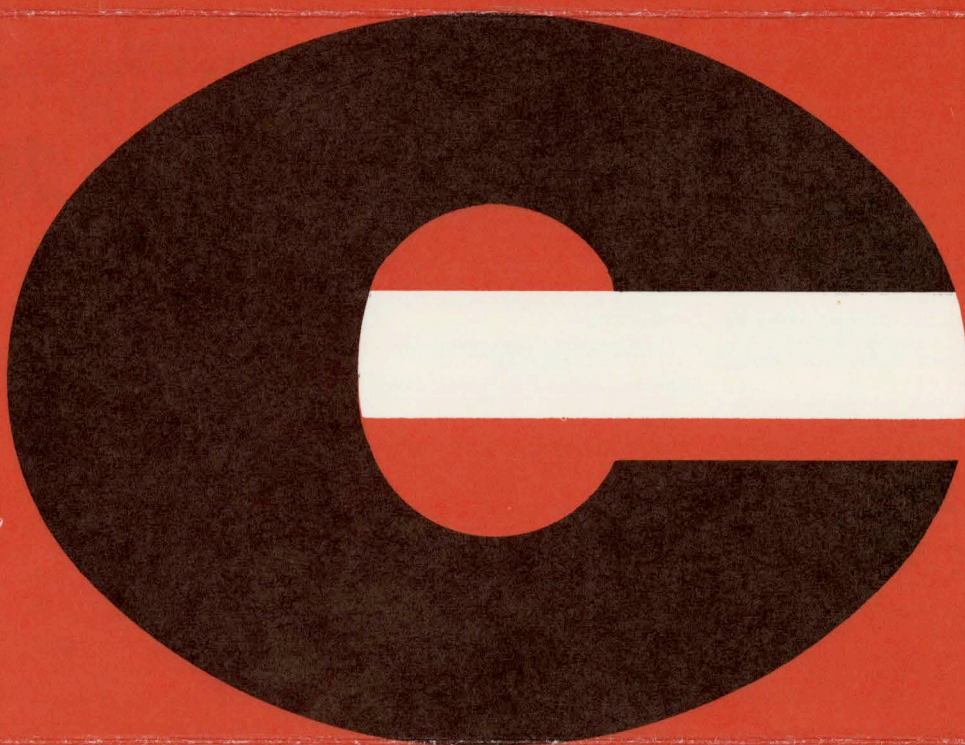


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**BASIC INSULATION BEHAVIOR**

Ionic Conduction in Insulation — A. H. Sharbaugh, General Elec. Co.  
 Polar Polymers — J. D. Hoffman, National Bur. Stds.  
 Dielectric Behavior of Glasses and Ceramics — Willis Barney, Corning Glass Co.  
 Statistical Methods for Predicting Electric Breakdown — W. L. Gore, W. L. Gore Associates.  
 Corona Discharges and Their Effects on Insulation — T. W. Dakin, Westinghouse Elec. Corp.

**TEMPERATURE CLASSIFICATION AND THERMAL ENDURANCE**

Fundamental Aspects for Temperature Classification and Thermal Endurance — G. L. Moses, Westinghouse Elec. Corp.  
 Thermal Evaluation Test Procedures for Materials — J. F. Dexter, Dow Corning Corp.  
 Insulation System Evaluation for Rotating Machines — J. C. Botts, Westinghouse Elec. Corp., East Pittsburgh, Pa.  
 Transformer Insulation System Evaluation — F. J. Vogel & W. Farneth, Allis-Chalmers Mfg. Co.  
 Users Viewpoint Concerning Thermal Evaluation & Temperature Class — H. Halperin, Commonwealth Edison Co.

**AGING TECHNIQUES**

End User Comments — Vern Honsinger, Allis-Chalmers Manufacturing Co., Norwood, Ohio.  
 Progressive Temperature Test — A New Approach for Screening Insul. Syst. — G. I. Duncan, General Electric Co.  
 The Significance of Oxygen Permeability of Electrical Insulation Systems in Determining Thermal Endurance — J. T. Wilson & E. Mohaupt, Harnischfeger Corp.  
 Thermal Aging Studies of Solenoid Coil Insulation Systems — H. P. Walker, Bureau of Ships, Navy Dept. & R. J. Flaherty, U. S. Naval Engrg. Experiment Station.  
 A Method for Heat Aging and Evaluating Thermal Endurance of Coated Sleeving — H. G. Steffens, Natvar Corp.  
 A Discussion of the Application of Regression Analysis to Thermal Eval. — T. Orbeck, Westinghouse Elec. Corp.

**INSULATION RESISTANCE MEASUREMENTS**

Introductory Remarks — A. H. Scott, National Bur. Stds.,  
 Instrumentation for Insulation Resistance Measurements — A. Blanck, Picatinny Arsenal.  
 Electrodes for Insulation Resistance Measurements — A. Blanck, Picatinny Arsenal.

Conditioning for Insulation Resistance Measurements — K. Wechsler, Westinghouse Elec. Corp.

Interpretation & Significance of Insulation Resistance Measurements — C. Craig, Sperry Gyroscope Co.

The Field Testing of Electrical Insulation by D-C Methods — E. B. Curdts, James G. Biddle Co.

**INTERNATIONAL INSULATION TECHNOLOGY**

Keynote — K. N. Mathes, General Electric Co.  
 The Importance of British Standards in the Appl. of Elect. Insulation — W. H. Devenish, Electrical Research Association Laboratory, Leatherhead, England  
 Mica Paper and Its Application in Europe — Dr. P. Bayard, ACEC, Charleroi, Belgium  
 Development of Electrical Insulation for Large Rotating Machines in Japan — S. Hyakutake, Toshiba, Yokohama, Japan.  
 The Use of Polystyrene Film in Power Capacitors — C. Bozzini & Dr. P. Bayard, ACEC, Charleroi, Belgium.

**DRY TYPE TRANSFORMERS**

Keynote — G. A. Monito, Westinghouse Electric Corp.  
 Survey of Past, Present and Proposed Materials and Insulation Systems for Dry Type Transformers — J. F. Dexter & L. A. Teichthesen, Dow Corning.

Improved Asbestos-reinforced Laminates — C. L. Rohn & N. Edgerton, Johns-Manville Products.  
 Heat & Moisture Resistant Resins for Varnishes & Molding Materials — J. L. Thomas, Food Machinery & Chemical Corp.

**THE FUTURE OF SWITCHGEAR INSULATION**

Keynote — W. H. Lane, Allis-Chalmers Mfg. Co.  
 The Importance of Low Dissipation Factor Track Resistant Insulation in Switchgear — L. L. Mankoff, General Electric Co.  
 Dippable Insulation Systems for Switchgear — W. C. Hosford & C. Fazekas, Metal & Thermit Corp.  
 Insulation for Structural Use in Switchgear — G. F. Fratto, Glastic Corp.

**ENCAPSULATED DISTRIBUTION TRANSFORMERS**

Keynote — W. A. McMorris, General Elec. Co.  
 End User Comments — W. A. Whittlesey — W. Mass. Elec. Co.  
 Epoxy Resins for Encapsulated Transformers — F. E. Pschorr & J. R. Weschler, Ciba Prod. Corp.  
 HT-1 A New High Temperature Electrical Insulation — W. R. Clay, E. I. duPont deNemours & Co.

**INTEGRAL HP MOTORS—HIGH TEMPERATURE PERFORMANCE**

Keynote—High Temperature Performance — W. B. Penn, General Electric Co.  
 An Evaluation of Insulation Systems Based on Polymer "ML" — F. E. Schweitzer, J. R. Chalmers, D. M. Glenn, M. Greif, E. I. duPont deNemours & Co.  
 Insulation Evaluation Techniques for Motors Used on Heavy Duty Portable Tools — D. N. Summerfield & A. F. Gawron, Skil Corp.  
 High Temperature Magnet Wires and Their Application in Rotating Equip. — W. W. Pendleton, Donald Devries, Anaconda Wire & Cable Co.  
 Evaluation of Traction Motor Field Coil Insulation Systems — C. W. Paxton & J. F. Dexter, Dow Corning Corp.

**ENCAPSULATED MOTORS**

Keynote — Encapsulated Motors — W. G. Stiffler, Reliance Elec. & Engr. Co.  
 End User Comments — W. D. Cox, Dow Chemical Corp.  
 Systems Evaluation of Epoxy Molded Coils — J. A. Foerster, Wabash Magnetics, Inc.  
 New Insulation System for D-C Field Coils — W. B. Penn & R. F. Sharrow, General Elec. Co.  
 Performance of Encapsulated Random Wound Induction Coils — C. W. Paxton & W. A. Pauwels, Dow Corning Corp.  
 A Study of Dip Encapsulated Motorettes Under Various Environmental Conditions — Leizor Balk & Francis Alessi, Sterling Varnish Co.

**FRACTIONAL HORSEPOWER MOTORS**

Keynote — Fractional Horsepower Motors — W. T. Gordon, Westinghouse Elec. Corp.  
 Formulating, Testing & Applying Varnish for High Speed Armatures — J. P. Haughney, Sherwin Williams Co.  
 Synthetic Fiber Insulating Papers for Class B & F Systems — G. R. Traut, R. C. Berry, N. L. Greenman, Rogers Corporation.  
 Integral Insulation of F. H. P. Motors — Milton V. DeJean, General Electric Co.

Fluidized Bed Application of Epoxy Resin Insulation to Rotating Electrical Machinery — D. L. Slater, Armstrong Resin, Inc.

**SERVICING & MAINTENANCE OF ROTATING MACHINERY**

Keynote — The Modern Repair Shop — T. C. Keegan, Jr., Federal Insulation Co.  
 An Approach to the Maintenance of Adequate Resistance Levels on DC Mach. — C. M. Thorp., Westinghouse Elec. Corp.  
 Insulation Systems in Heavy Duty Electrical Equipment — J. A. Bell & J. Logan, General Motors Corp.

Magnet Wire Windability — E. W. Daszewski, Essex Wire Corp.

**RESINS FOR ELECTRONIC PACKAGING**

New Developments in Trends & Resins for Electronic Packaging — M. M. Lee, Lepoxy Plastics.  
 A Flexible Silicone Resin for Embedding Electronic Circuitry — D. F. Christensen, M. E. Nelson, & R. L. Spraezt, Dow Corning Corporation.  
 Effect of Flame Retardant Modifiers on Low Loss Epoxy Resin System for Use at 160°C. — F. T. Parr, Westinghouse Electric Corp.  
 Improved Thermal Shock Resistance of Epoxies. Advances in Epoxidized Polyolefins for Electronic Packaging Applications — C. W. Johnston, Food Machinery & Chemical Corp.  
 Evaluating Flexible Epoxy Systems — C. Cialdella, Hysol Corporation.  
 Epoxy Resins in High Voltage Applications — E. N. Dorman, Ciba Products Corp.

**ENCAPSULATED MAGNETIC COMPONENTS**

The State of the Encapsulated Transformer — R. B. Feuchtbaum, Hughes Aircraft Co., Culver City, Cal.  
 Silicone Electronic Packaging Materials — R. L. Spraezt & D. F. Christensen, Dow Corning, Midland, Mich.  
 Resilient Epoxies Applied to Magnetic Components — J. Delmonte, Furance Plastics, Inc.  
 The Dielectric Strength of Epoxy Embedding Compounds — C. C. Scheid, General Electric Co.

The Role of the Resin Formulator in Magnetic Component Manufacture — P. Van Amburgh, EVRA, Inc.

**BATTERY — SEPARATOR SESSION**

Keynote — H. P. Gregor, Polytechnic Institute of Brooklyn, New York  
 End User Comments — H. Zahn, Gould-Nat'l Batteries, Inc.  
 Structure & Properties of Storage — Battery Separators — J. A. Orsino, E. J. Dunn, Jr. & W. J. Bundy, National Lead Company, Research Laboratories.  
 Ion Exchange Membranes for Fuel Cells — E. Oster, General Electric Company,

**ELECTROLYTIC CAPACITORS**

New Thin Film Capacitors — R. C. Sprague, Sprague Electric Co.  
 Government Specifications on Capacitors — A. B. Pratt, U. S. Signal Corp.  
 Thin Film Dielectrics — F. S. Maddocks, IBM, Fed. System Div., Com. Cont. Ctr.  
 Electrolytic Capacitors — Otto Weed, Kaweck Chemical Corporation.

**MONDAY — FEBRUARY 19**

A.M. Private Meetings  
 3:00 P.M.—5:30 P.M. Marketers Meetings  
 6:30 P.M.—8:30 P.M. Marketers Dinner  
 8:30 P.M. Get-Together Night

**TUESDAY — FEBRUARY 20**

9:00 A.M.— 4:30 P.M. Technical Sessions  
 12 Noon — 1:30 P.M. NEMA Luncheon  
 1:30 P.M.—10:00 P.M. Exhibits  
 (Dinner break 5:30 P.M.—7:00 P.M.)

**WEDNESDAY — FEBRUARY 21**

9:00 A.M.—11:30 A.M. Technical Sessions  
 12 Noon — 1:30 P.M. Buffet Luncheon  
 1:30 P.M.— 5:30 P.M. Exhibitors Afternoon  
 6:00 P.M.— 9:30 P.M. Banquet

**THURSDAY — FEBRUARY 22**

9:00 A.M.— 4:30 P.M. Technical Sessions  
 12 Noon AIEE Luncheon  
 12 Noon — 5:00 P.M. Exhibits

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